



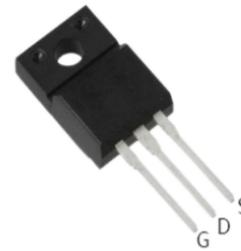
# DMF13N50

## 13A, 500V N-CHANNEL POWER MOSFET

### 1.Features

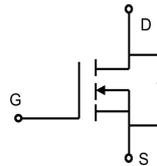
- $V_{DS}$  500V
- $I_D$  13A
- $R_{DS(on)}$ (at  $V_{GS}=10V$   $I_D=6.5A$ ) 0.45 $\Omega$ (Typ)  
0.5 $\Omega$ (Max)

ITO-220



### 2.Mechanical Data

- Case:Molded Plastic, ITO-220;
- Epoxy:UL 94V-0 rate flame retardant
- Terminals:Plated Leads Solderable per MIL-STD-750,Method-2026.
- Marking: marked on body.
- Mounting Position : Any.



1. Gate
2. Drain
3. Source

### 3.Maximum Ratings and Electrical Characteristics

Electrical Characteristics ( $T_J=25^\circ\text{C}$  unless otherwise noted)

Characteristics		Symbol	Ratings	Unit
Drain-Source Voltage		$V_{DS}$	500	V
Gate-Source Voltage		$V_{GS}$	$\pm 30$	V
Drain Current-Continuous	$T_C=25^\circ\text{C}$	$I_D$	13	A
	$T_C=100^\circ\text{C}$		7.9	
Power Dissipation( $T_C=25^\circ\text{C}$ )		$P_D$	50	W
Single Pulsed Avalanche Energy (Note1)		$E_{AS}$	500	mJ
Avalanche Current (note2)		$I_{AR}$	13	A
Junction Temperature(Max)		$T_J$	150	$^\circ\text{C}$
Junction and Storage Temperature Range		$T_{stg}$	-55 to +150	$^\circ\text{C}$
Maximum lead temperature for soldering purposes, 1/8" from case for 5 seconds		TL	300	$^\circ\text{C}$
<b>Thermal Characteristics</b>				
Parameter	Symbol	Typ	Max	Unit
Thermal Resistance, Junction-to-Case	$R_{\theta JC}$	-	2.5	$^\circ\text{C/W}$
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	-	62.5	$^\circ\text{C/W}$



Characteristics	Symbol	Test conditions	Min	TYP	Max	Unit
<b>Off Characteristics</b>						
Drain-Source Breakdown Voltage	$BV_{DSS}$	$V_{GS}=0V, I_D=250\mu A$	500	-	-	V
Breakdown Voltage Temperature Coefficient	$\frac{\Delta BV_{DSS}}{\Delta T_J}$	$I_D=250\mu A$ , Reference to 25°C	-	0.65	-	V/°C
Drain-Source Leakage Current	$I_{DSS}$	$V_{DS}=500V, V_{GS}=0V$	-	-	1	$\mu A$
		$V_{DS}=400V, T_J=125^\circ C$	-	-	100	$\mu A$
Gate-Source Leakage Current	$I_{GSS}$	$V_{GS}=30V, V_{DS}=0V$	-	-	100	nA
Gate-Source Leakage Current	$I_{GSS}$	$V_{GS}=-30V, V_{DS}=0V$	-	-	-100	nA
<b>On Characteristics</b>						
Gate Threshold Voltage	$V_{GS(th)}$	$V_{GS}=V_{DS}, I_D=250\mu A$	2	-	4	V
Drain-Source On-State Resistance	$R_{DS(on)}$	$V_{GS}=10V, I_D=6.5A$	-	0.45	0.5	$\Omega$
<b>DYNAMIC PARAMETERS</b>						
Input Capacitance	$C_{iss}$	$V_{DS}=25V$ $V_{GS}=0V$ $f=1.0MHz$	-	1680	-	pF
Output Capacitance	$C_{oss}$		-	120	-	
Reverse Transfer Capacitance	$C_{rss}$		-	12	-	
<b>SWITCHING PARAMETERS</b>						
Turn-on Delay Time	$t_{d(on)}$	$V_{DD}=250V, V_{GS}=13V$ $R_G=25\Omega$ ; (Note 3.4)	-	40	-	ns
Turn-on Rise Time	$t_r$		-	140	-	
Turn-off Delay Time	$t_{d(off)}$		-	125	-	
Turn-off Fall Time	$t_f$		-	85	-	
Total Gate Charge	$Q_g$	$V_{DS}=400V, I_D=13A$ $V_{GS}=10V$ (Note 3.4)	-	50	-	nC
Gate-Source Charge	$Q_{gs}$		-	9.8	-	
Gate-Drain Charge	$Q_{gd}$		-	18.5	-	
<b>SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS</b>						
Continuous Source Current	$I_S$	-	-	-	13	A
Pulsed Source Current	$I_{SM}$		-	-	52	
Diode Forward Voltage	$V_{SD}$	$I_D=13A$ ,	-	-	1.4	V
Reverse Recovery Time	$T_{rr}$	$I_S=13A, V_{GS}=0V$ , $dI/dt=100A/\mu S$ (Note3)	-	420	-	ns
Reverse Recovery Charge	$Q_{rr}$		-	4.2	-	nC

#### 4. Ordering Information

Part No.	Package	Marking
DMF9N90	ITO-220	DMF9N90

**Notes:**

1.  $L=17.1mH, I_{AS}=13A, V_{DD}=50V, R_G=25\Omega$ , starting  $T_J=25^\circ C$
2. Pulse width limited by maximum junction temperature
3. Pulse Test: Pulse width  $\leq 300\mu s$ , Duty cycle  $\leq 2\%$
4. Essentially independent of operating temperature



### 5. Rating And Characteristic Curves

Fig.1 Typical Output Characteristics,  $T_c=25^\circ\text{C}$

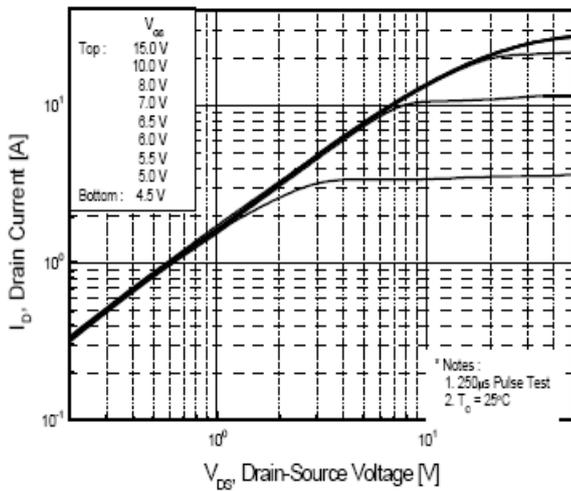


Fig.2 On-Resistance Vs. Drain Current and Gate Voltage

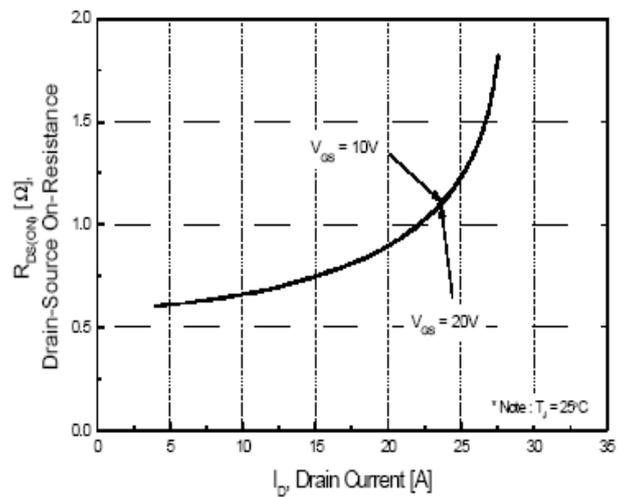


Fig.3 Normalized On-Resistance Vs. Temperature

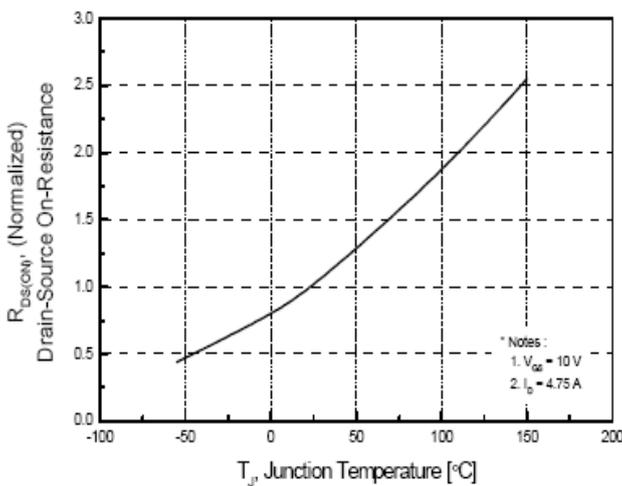


Fig.4 Typical Source-Drain Diode Forward Voltage

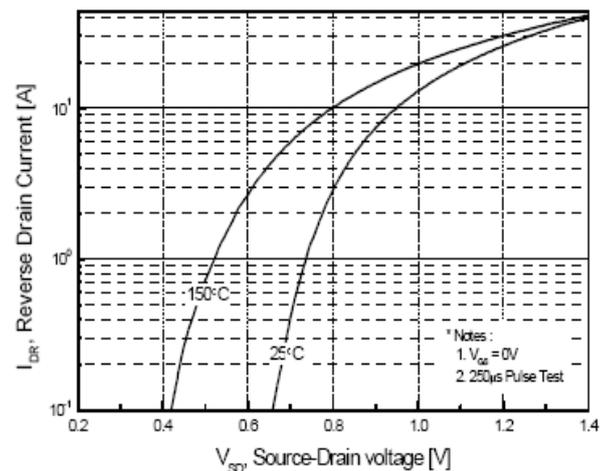


Fig.5 Maximum Drain Current Vs. Case Temperature

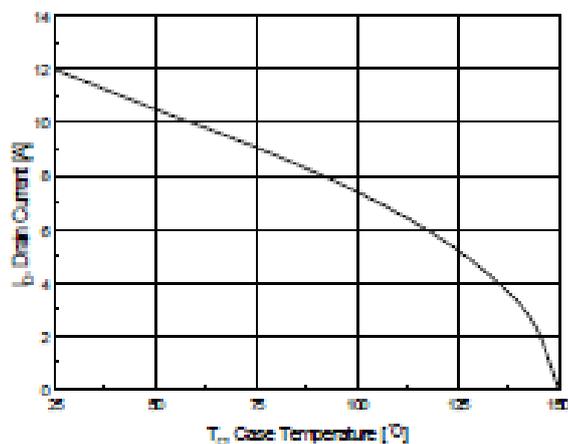
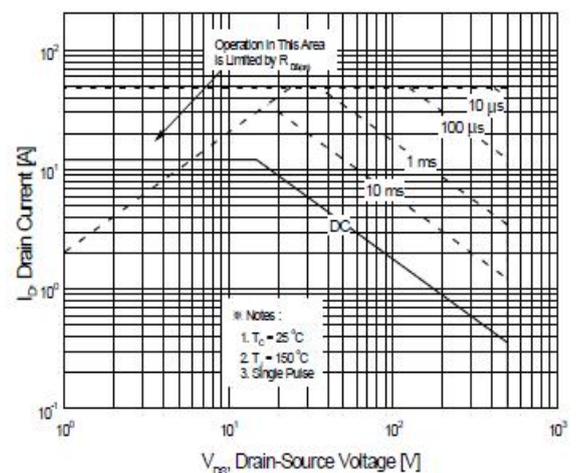
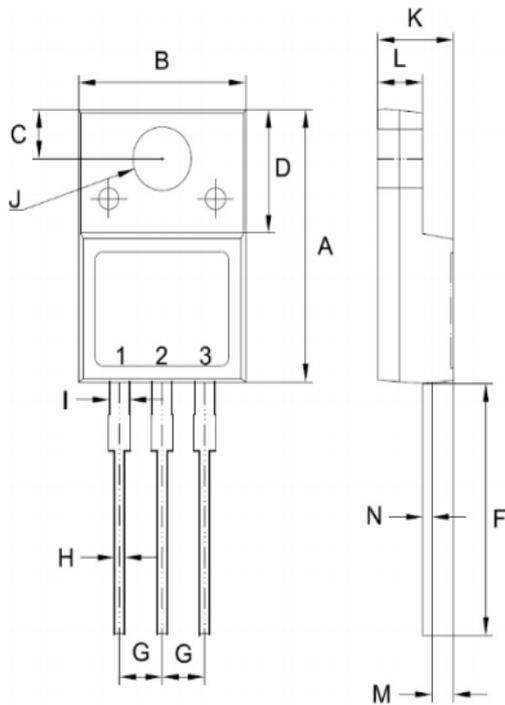


Fig.6 Maximum Safe Operating Area





### 6. Dimensions

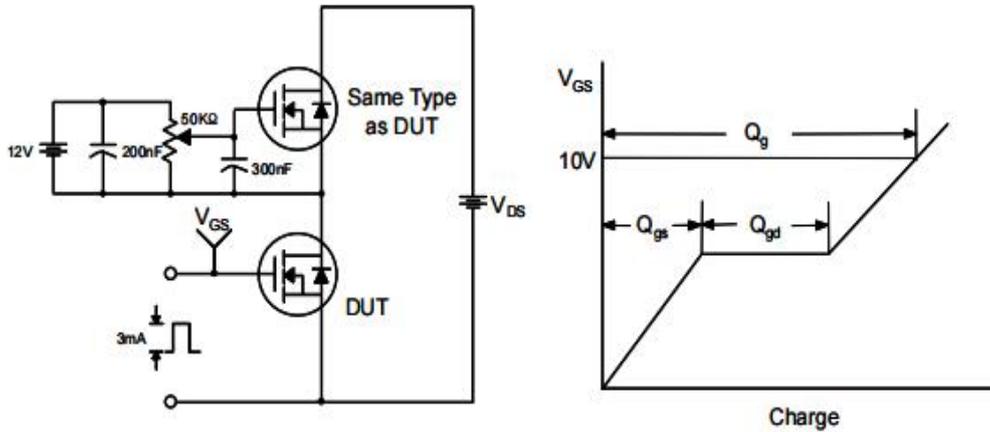


Dimensions	Inches		Millimeters	
	Min	Max	Min	Max
A	0.571	0.642	14.50	16.30
B	0.374	0.413	9.50	10.50
C	0.098	0.140	2.50	3.55
D	0.248	0.287	6.30	7.30
F	0.503	0.551	12.78	14.00
G	0.093	0.108	2.35	2.75
H	0.012	0.037	0.30	0.95
I	0.035	0.059	0.90	1.50
J	0.118	0.150	3.00	3.80
K	0.167	0.198	4.24	5.02
L	0.091	0.115	2.30	2.92
N	0.018	0.025	0.45	0.63

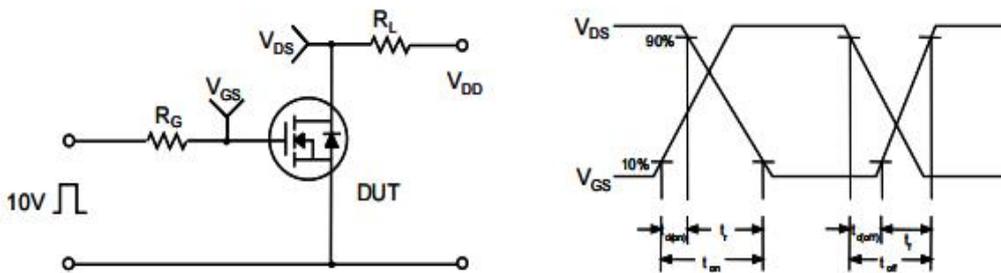


### 7. Test circuits

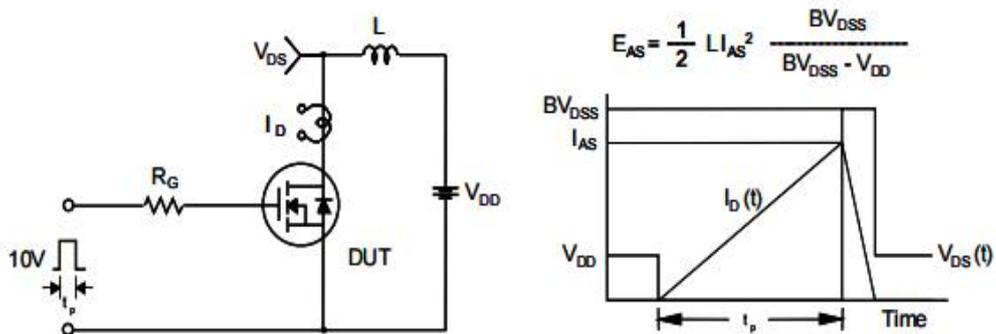
#### Gate Charge Test Circuit & Waveform



#### Resistive Switching Test Circuit & Waveforms

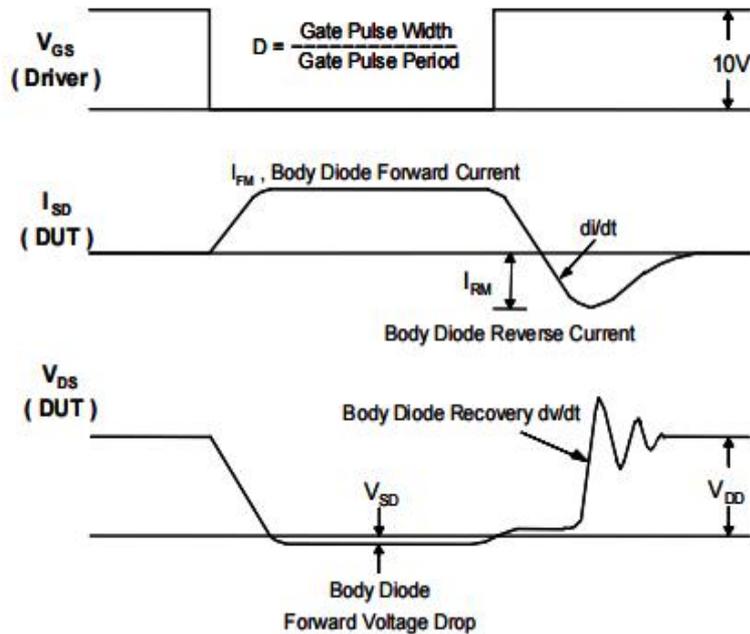
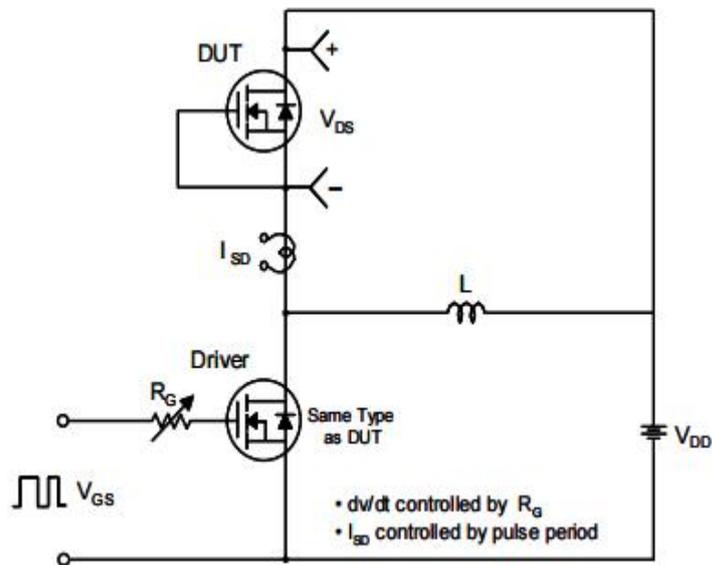


#### Unclamped Inductive Switching Test Circuit & Waveforms





### Peak Diode Recovery $dv/dt$ Test Circuit & Waveforms





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